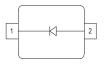


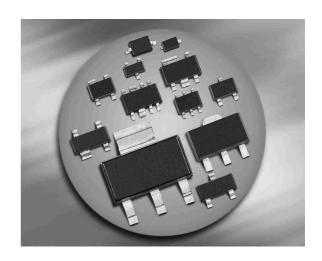
Silicon Tuning Diode

- For UHF-TV-tuners
- High capacitance ratio
- Low series inductance
- Low series resistance
- Excellent uniformity and matching due to "in-line" matching assembly procedure
- Pb-free (RoHS compliant) package



BB535 BB555/-02V





Туре	Package	Configuration	L S(nH)	Marking
BB535	SOD323	single	1.8	white S
BB555	SCD80	single	0.6	ВВ
BB555-02V	SC79	single	0.6	В

Maximum Ratings at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage	V_{R}	30	V
Peak reverse voltage	V_{RM}	35	
$R \ge 5 k\Omega$			
Forward current	I _F	20	mA
Operating temperature range	T_{op}	-55 150	°C
Storage temperature	$T_{ m stg}$	-55 150	



Electrical Characteristics at $T_A = 25$ °C, unless otherwise specified

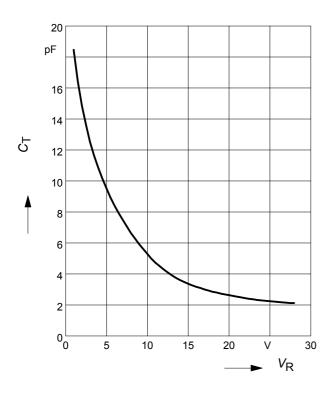
Parameter	Symbol		Values			
		min.	typ.	max.		
DC Characteristics					•	
Reverse current	I_{R}				nA	
<i>V</i> _R = 30 V		-	-	10		
V_{R} = 30 V, T_{A} = 85 °C		-	-	200		
AC Characteristics						
Diode capacitance	C _T				pF	
$V_{R} = 1 \text{ V}, f = 1 \text{ MHz}$		17.5	18.7	20		
$V_{R} = 2 \text{ V}, f = 1 \text{ MHz}$		14.01	15	16.1		
$V_{R} = 25 \text{ V}, f = 1 \text{ MHz}$		2.05	2.24	2.4		
$V_{R} = 28 \text{ V}, f = 1 \text{ MHz}$		1.9	2.1	2.3		
Capacitance ratio	C _{T1} /C _{T28}	8.2	8.9	9.8	-	
$V_{R} = 1 \text{ V}, V_{R} = 28 \text{ V}, f = 1 \text{ MHz}$						
Capacitance ratio	C_{T2}/C_{T25}	6	6.7	7.5		
$V_{R} = 2 \text{ V}, V_{R} = 25 \text{ V}, f = 1 \text{ MHz}$						
Capacitance matching ¹⁾	$\Delta C_{T}/C_{T}$				%	
V_{R} = 1V to 28V, f = 1 MHz, 7 diodes sequence,						
BB535		-	-	2.5		
V_R = 1V to 28V, f = 1 MHz, 4 diodes sequence,						
BB555/-02V		-	0.15	1		
V_R = 1V to 28V, f = 1 MHz, 7 diodes sequence,						
BB555/-02V		-	0.25	2		
Series resistance	$r_{\rm S}$	-	0.58	0.75	Ω	
$V_{R} = 3 \text{ V}, f = 470 \text{ MHz}$						
Series inductance	L _S	-	0.6	-	nH	

¹For details please refer to Application Note 047



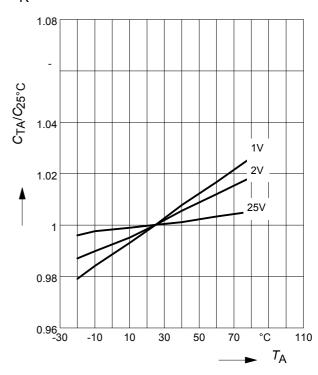
Diode capacitance $C_T = f(V_R)$

f = 1MHz

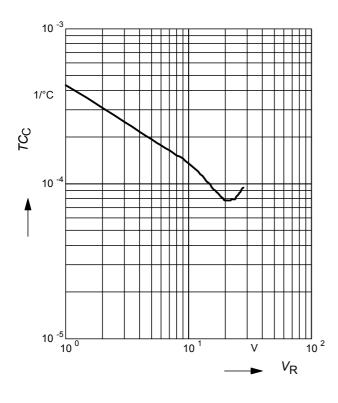


Normalized diode capacitance

 $C_{(TA)}/C_{(25^{\circ}C)} = f(T_A); f = 1MHz$ $V_R = Parameter$

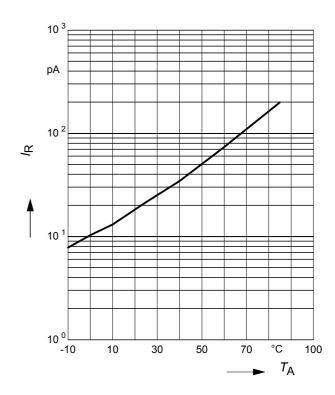


Temperature coefficient of the diode capacitance $T_{Cc} = f(V_R)$



Reverse current $I_R = f(T_A)$

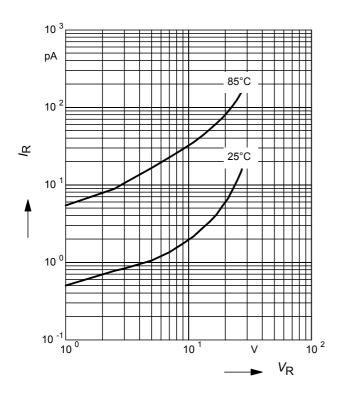
$$V_{R} = 28 \text{ V}$$





Reverse current $I_R = f(V_R)$

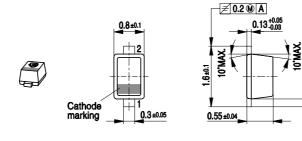
 T_A = Parameter



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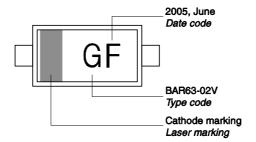
Package Outline



Foot Print



Marking Layout (Example)

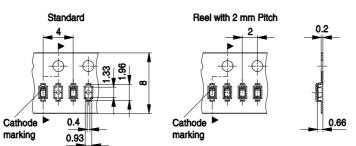


Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel

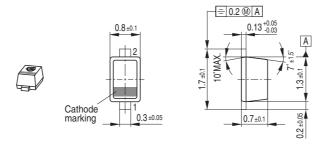
Reel ø180 mm = 8.000 Pieces/Reel (2 mm Pitch)

Reel ø330 mm = 10.000 Pieces/Reel





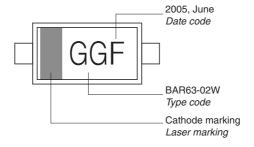
Package Outline



Foot Print



Marking Layout (Example)

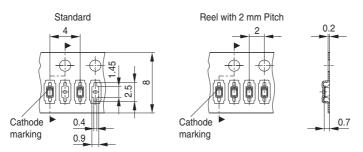


Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel

Reel ø180 mm = 8.000 Pieces/Reel (2 mm Pitch)

Reel ø330 mm = 10.000 Pieces/Reel





Date Code marking for discrete packages with one digit (SCD80, SC79, SC75¹⁾) CES-Code

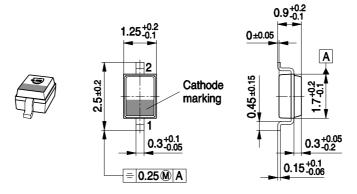
Month	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014
01	а	р	Α	Р	а	р	Α	Р	а	р	Α	Р
02	b	q	В	Q	b	q	В	Q	b	q	В	Q
03	С	r	С	R	С	r	С	R	С	r	С	R
04	d	S	D	S	d	S	D	S	d	S	D	S
05	е	t	Е	Т	е	t	Е	Т	е	t	Е	Т
06	f	u	F	U	f	u	F	U	f	u	F	U
07	g	٧	G	V	g	٧	G	٧	g	٧	G	V
08	h	Х	Н	Х	h	Х	Н	Х	h	Х	Н	Х
09	j	У	J	Υ	j	у	J	Υ	j	У	J	Y
10	k	Z	K	Z	k	Z	K	Z	k	Z	K	Z
11	I	2	L	4	I	2	L	4	I	2	L	4
12	n	3	N	5	n	3	N	5	n	3	N	5

¹⁾ New Marking Layout for SC75, implemented at October 2005.

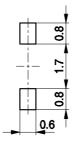
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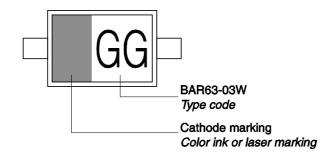
Package Outline



Foot Print

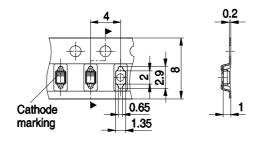


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel





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